

MOSFETs Silicon N-channel MOS (U-MOSIX-H)

TPH1R204PL

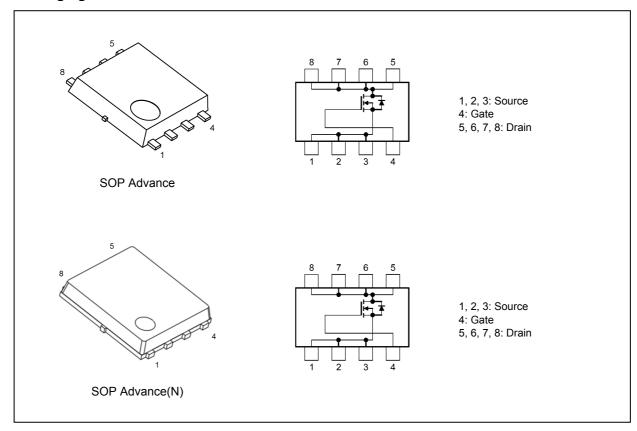
1. Applications

- · High-Efficiency DC-DC Converters
- Switching Voltage Regulators

2. Features

- (1) High-speed switching
- (2) Small gate charge: $Q_{SW} = 17 \text{ nC (typ.)}$
- (3) Small output charge: $Q_{oss} = 56 \text{ nC (typ.)}$
- (4) Low drain-source on-resistance: $R_{DS(ON)} = 1.0 \text{ m}\Omega$ (typ.) ($V_{GS} = 10 \text{ V}$)
- (5) Low leakage current: $I_{DSS} = 10 \mu A \text{ (max)} \text{ (V}_{DS} = 40 \text{ V)}$
- (6) Enhancement mode: $V_{th} = 1.4 \text{ to } 2.4 \text{ V } (V_{DS} = 10 \text{ V}, I_D = 0.5 \text{ mA})$

3. Packaging and Internal Circuit



The package can be selected according to your preference. For details, please contact your TOSHIBA sales representative.

Start of commercial production



4. Absolute Maximum Ratings (Note) (Ta = 25 °C unless otherwise specified)

Characteristics			Symbol	Rating	Unit
Drain-source voltage			V_{DSS}	40	V
Gate-source voltage			V_{GSS}	±20	
Drain current (DC)	$(T_c = 25 ^{\circ}C)$	(Note 1), (Note 2)	Ι _D	150	Α
Drain current (DC)	(Silicon limit)	(Note 1), (Note 2)	I_D	246	Α
Drain current (pulsed)	(t = 100 μs)	(Note 1)	I _{DP}	500	Α
Power dissipation	(T _c = 25 °C)		P_D	132	W
Power dissipation		(Note 3)	P_{D}	3	W
Power dissipation		(Note 4)	P_D	0.96	W
Single-pulse avalanche energy		(Note 5)	E _{AS}	127	mJ
Single-pulse avalanche current		(Note 5)	I _{AS}	120	Α
Channel temperature			T _{ch}	175	°C
Storage temperature			T _{stg}	-55 to 175	°C

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

5. Thermal Characteristics

Characteristics	Symbol	Max	Unit		
Channel-to-case thermal resistance	(T _c = 25 °C)		R _{th(ch-c)}	1.13	°C/W
Channel-to-ambient thermal resistance	(T _a = 25 °C)	(Note 3)	R _{th(ch-a)}	50	
Channel-to-ambient thermal resistance	(T _a = 25 °C)	(Note 4)	R _{th(ch-a)}	156	

Note 1: Ensure that the channel temperature does not exceed 175 °C.

Note 2: Limited by package limit. Silicon chip capability is 246 A. $(T_c = 25 \, ^{\circ}C)$

Note 3: Device mounted on a glass-epoxy board (a), Figure 5.1

Note 4: Device mounted on a glass-epoxy board (b), Figure 5.2

Note 5: V_{DD} = 32 V, T_{ch} = 25 °C (initial), L = 0.0068 mH, I_{AS} = 120 A

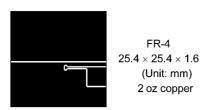
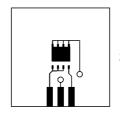


Fig. 5.1 Device Mounted on a Glass-Epoxy Board (a)



FR-4 25.4 × 25.4 × 1.6 (Unit: mm) 2 oz copper

Fig. 5.2 Device Mounted on a Glass-Epoxy Board (b)

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.



6. Electrical Characteristics

6.1. Static Characteristics (T_a = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current	I _{GSS}	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±0.1	μΑ
Drain cut-off current	I _{DSS}	V _{DS} = 40 V, V _{GS} = 0 V	_		10	
Drain-source breakdown voltage	V _{(BR)DSS}	I _D = 10 mA, V _{GS} = 0 V	40			V
	V _{(BR)DSX}	$I_D = 10 \text{ mA}, V_{GS} = -20 \text{ V}$	25	_	_	
Gate threshold voltage	V_{th}	V_{DS} = 10 V, I_{D} = 0.5 mA	1.4		2.4	
Drain-source on-resistance	R _{DS(ON)}	$V_{GS} = 4.5 \text{ V}, I_D = 50 \text{ A}$	_	1.5	2.1	mΩ
		V _{GS} = 10 V, I _D = 50 A	_	1.0	1.24	

6.2. Dynamic Characteristics (T_a = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Input capacitance	C _{iss}	V _{DS} = 20 V, V _{GS} = 0 V, f = 1 MHz	_	5500	7200	pF
Reverse transfer capacitance	C_{rss}		_	93		
Output capacitance	C _{oss}		_	1300		
Gate resistance	r _g	_	_	0.6	1.1	Ω
Switching time (rise time)	t _r	See Fig. 6.2.1	_	13		ns
Switching time (turn-on time)	t _{on}		_	33		
Switching time (fall time)	t _f		_	10	_	
Switching time (turn-off time)	t _{off}		_	58	_	

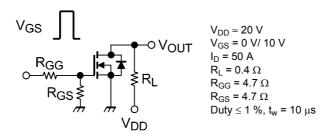


Fig. 6.2.1 Switching Time Test Circuit

6.3. Gate Charge Characteristics (T_a = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Total gate charge (gate-source plus	Q_g	$V_{DD} \approx 20 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 50 \text{ A}$		74		nC
gate-drain)		$V_{DD} \approx 20 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 50 \text{ A}$		34		
Gate-source charge 1	Q _{gs1}	$V_{DD} \approx 20 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 50 \text{ A}$		16		
Gate-drain charge	Q_{gd}			17	_	
Gate switch charge	Q_{SW}			17		
Output charge	Q _{oss}	V _{DS} = 20 V, V _{GS} = 0 V	_	56	_	

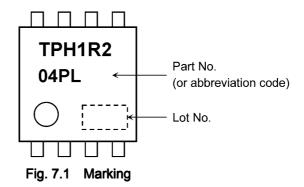


6.4. Source-Drain Characteristics (T_a = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Reverse drain current (pulsed) (Note 6)	I _{DRP} (t = 100 μs)	_	_	_	500	Α
Diode forward voltage	V_{DSF}	I _{DR} = 150 A, V _{GS} = 0 V		_	-1.2	V
Reverse recovery time	t _{rr}	$V_R = 20 \text{ V}, I_{DR} = 37.5 \text{ A}, V_{GS} = 0 \text{ V}, -dI_{DR}/dt = 100 \text{ A}/\mu\text{s}$	-	46	-	ns
Reverse recovery charge		$V_R = 20 \text{ V}, I_{DR} = 37.5 \text{ A}, V_{GS} = 0 \text{ V}, -dI_{DR}/dt = 100 \text{ A}/\mu\text{s}$		46		nC

Note 6: Ensure that the channel temperature does not exceed 175 °C.

7. Marking



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8. Characteristics Curves (Note)

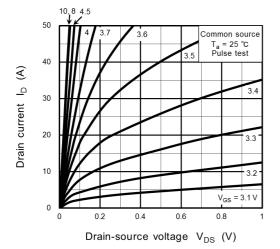


Fig. 8.1 I_D - V_{DS}

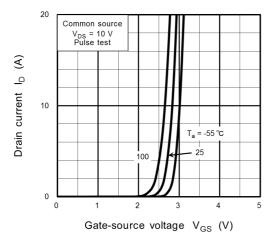


Fig. 8.3 I_D - V_{GS}

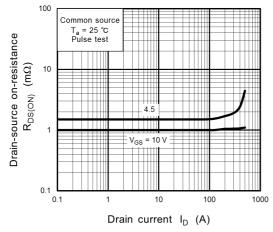


Fig. 8.5 R_{DS(ON)} - I_D

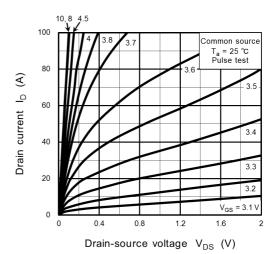


Fig. 8.2 $I_D - V_{DS}$

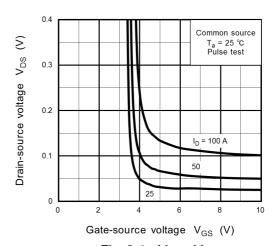


Fig. 8.4 V_{DS} - V_{GS}

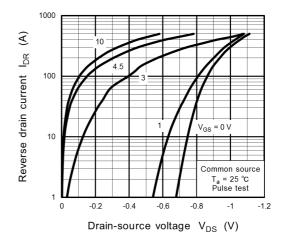


Fig. 8.6 IDR - VDS



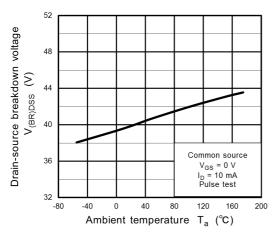


Fig. 8.7 V_{(BR)DSS} - T_a

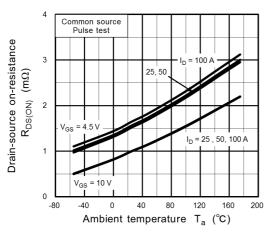


Fig. 8.9 R_{DS(ON)} - T_a

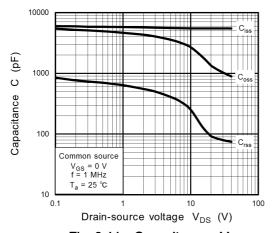


Fig. 8.11 Capacitance - V_{DS}

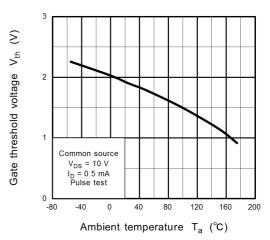


Fig. 8.8 V_{th} - T_a

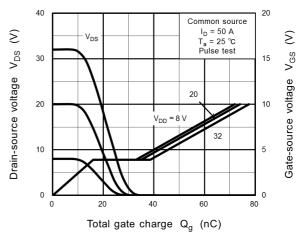


Fig. 8.10 Dynamic Input/Output Characteristics

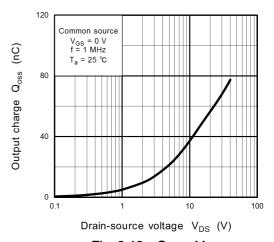


Fig. 8.12 Qoss - VDS



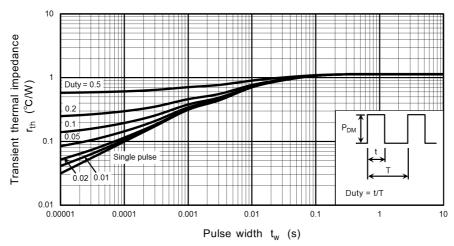


Fig. 8.13 r_{th} - t_w (Guaranteed Maximum)

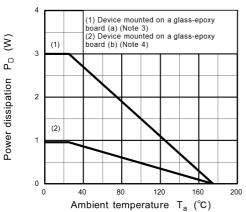


Fig. 8.14 P_D - T_a (Guaranteed Maximum)

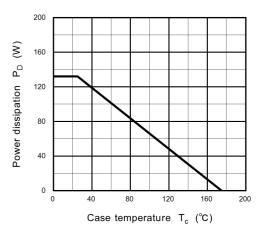


Fig. 8.15 P_D - T_c (Guaranteed Maximum)

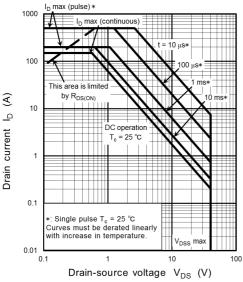


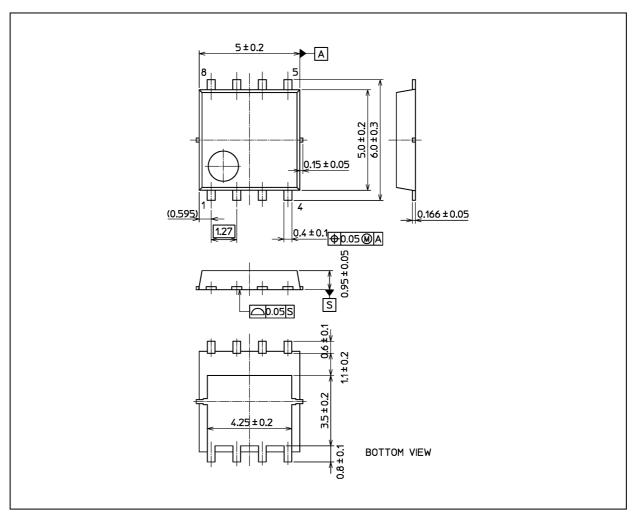
Fig. 8.16 Safe Operating Area (Guaranteed Maximum)

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



Package Dimensions

Unit: mm



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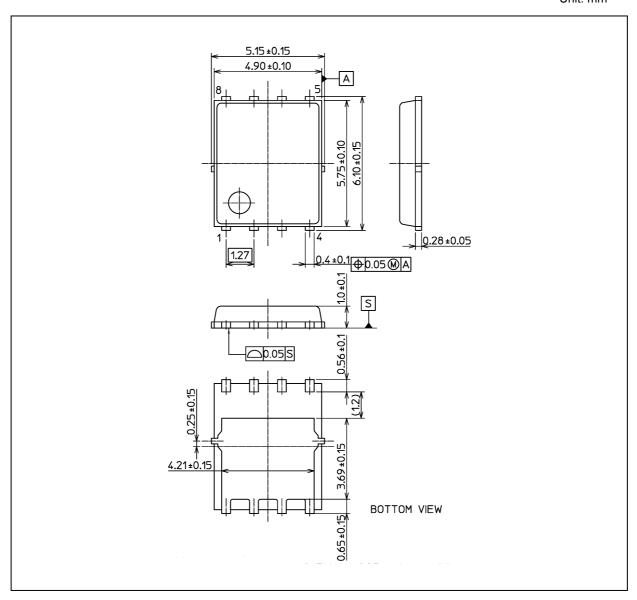
Weight: 0.079 g (typ.)

i	Package Name(s)
TOSHIBA: 2-5Q1S	
Nickname: SOP Advance	



Package Dimensions

Unit: mm



The package can be selected according to your preference. For details, please contact your TOSHIBA sales representative.

Weight: 0.105 g (typ.)

Package Name(s)
TOSHIBA: 2-5W1A
Nickname: SOP Advance(N)

Rev.4.0



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